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(54) Title: METHOD AND APPARATUS FOR DEBONDING A SUBMOUNTED SUBSTRATE

(57) Abstract: The present invention provides a debonding apparatus, a system comprising such apparatus, and methods for using such apparatus or system for the removal of flexible substrates (14) post-processing without damage to fabricated devices.

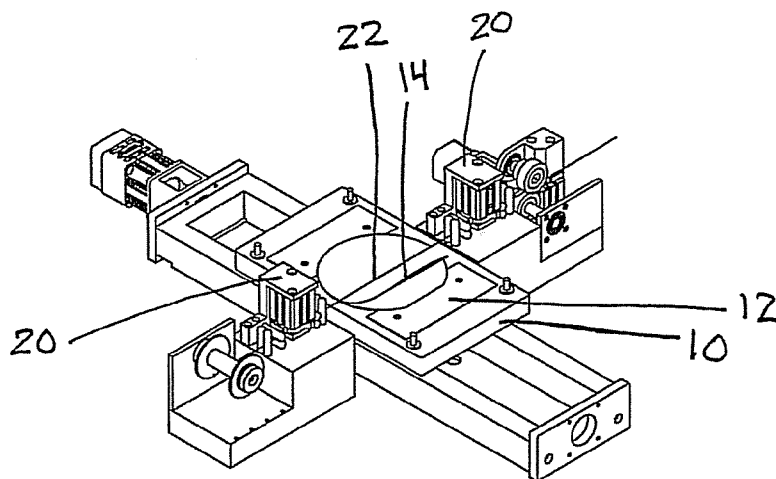


Figure 2



OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, —
MR, NE, SN, TD, TG).

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